

Surface Mounted Chip LED

Model No. :CL-SP170UDR

■ Features :

- Compatible with automatic placement equipment
- Compatible with reflow solder process

■ Applications :

- Automotive_Telecommunication
- Indicators
- LCD Back-lights
- Illuminations

Dice Material	Light Color	Lens Color
AlGaInP	Ultra High Red	Water Clear

Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Maximum	Unit
Power Dissipation	P _D	78	mW
Continuous Forward Current	I _F	30	mA
Peak Forward Current (1/10 Duty Cycle 0.1ms Pulse Width)	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Derating Linear From 25°C		0.4	mA/°C
Operating Temperature Range	T _{opr}	-30 to +80	°C
Storage Temperature Range	T _{stg}	-40 to +85	°C

Electrical / Optical Characteristics

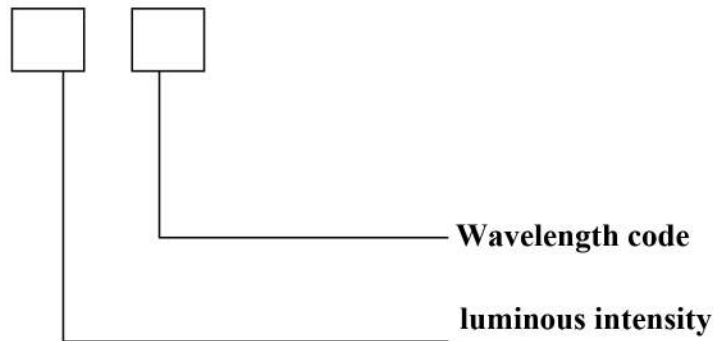
(Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	IF=20mA		2.10	2.60	V
Reverse Current	I _R	VR=5V			10	uA
Peak Emission Wavelength	λ _P	IF=20mA		655		nm
Dominant Wavelength	λ _D	IF=20mA		640		nm
Viewing Angle	2 θ 1/2	IF=20mA		130		Deg
Luminous Intensity	I _V	IF=20mA	20.0	55.0		mcd

ISSUE	DIMENSION NO :	VERSION :	DATE :
		C	2007/02/01
	APPROVAL :	CHECK :	EDIT :

◆ Packing coding principle

Notice: Bin code: luminous intensity / wavelength



◆ The Luminous Intensity Grade of Ultra High Red Chip-LED Products

● Test Condition : @ 20mA

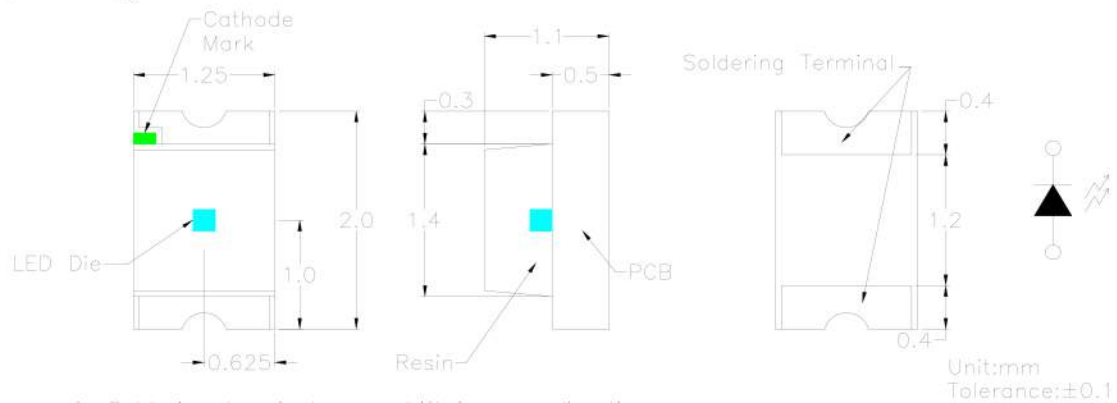
Range,mcd	Bin code
18/28.5	G
28.5/45	H
45/72	J
72/115	K
115/180	L

◆ Dominant Wavelength Grade of Ultra High Red Chip-LED Products

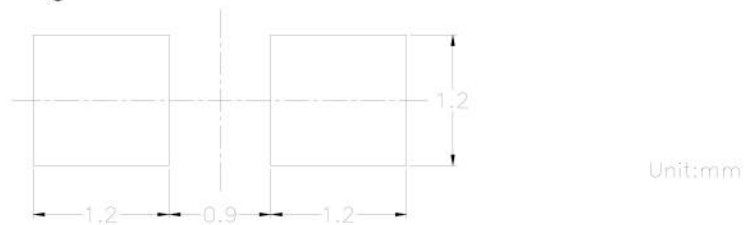
● I type @ 20mA

BIN	Range
1	624/632
2	632/640

◆ Package Dimensions of Device

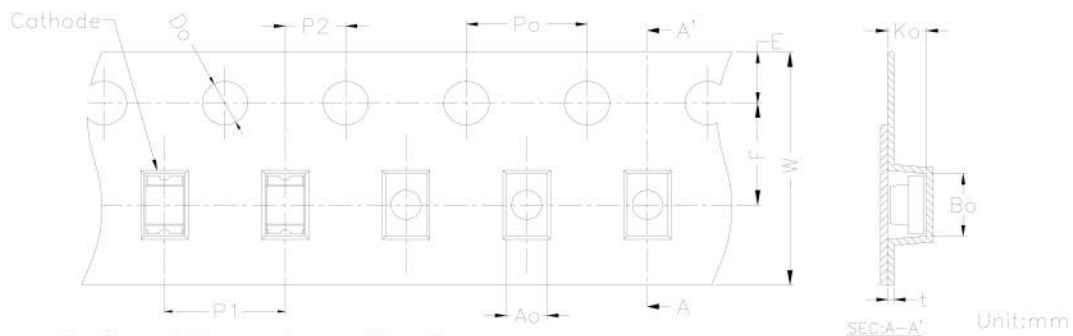


◆ Recommended Soldering Pad Dimensions

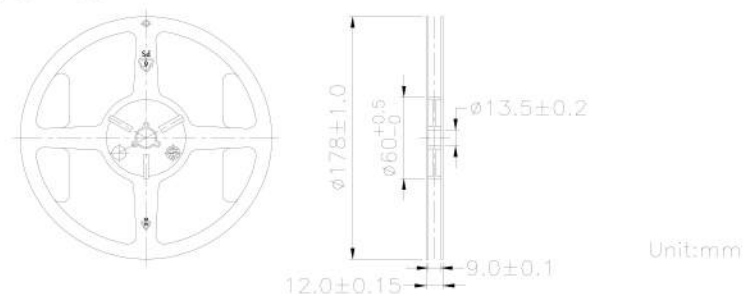


◆ Tape Specification : 3000pcs Per Reel

Packing Size													
Item	W	P1	E	F	D _ø	D1	P _ø	10P _ø	P2	A _ø	B _ø	K _ø	t
Spec.	8.00	4.00	1.75	3.50	1.50	1.00	4.00	40.00	2.00	1.40	2.25	1.35	0.23
Tolerance	±0.20	±0.10	±0.10	±0.05	+0.10 -0.00	±0.05	±0.05	±0.20	±0.05	±0.10	±0.10	±0.10	±0.05



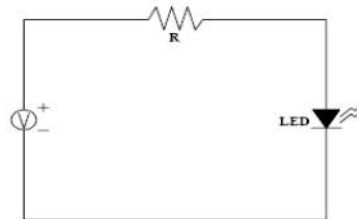
◆ Package Dimensions of Reel



◆ Precautions For Use :

- Over – current – proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)



- Storage

1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$, R.H.60% Max..
2. Once the package is opened, the products should be used within 72 hrs. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1 year (from production date) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $80^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 24hrs.

◆ Soldering Iron :

- Temperature at tip of iron : 300°C Max. (25W Max.)
- Soldering time : $5 \pm 1\text{sec}$.

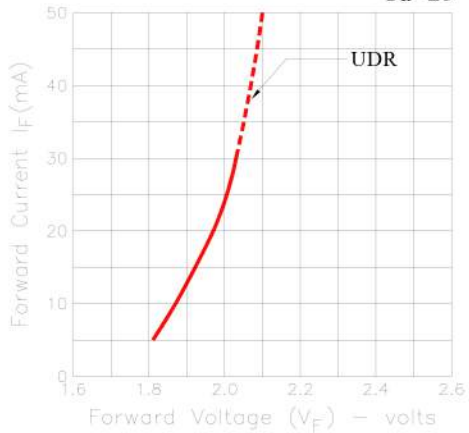
◆ Wave Soldering Temp. / Time :

Temp.($^{\circ}\text{C}$)		Time(Sec)	
a	25	T1~T2	60 ± 20
b	130 ± 10	T2~T3	
c	185	T3~T6	
d	250 ± 3	T4~T5	3 ± 2

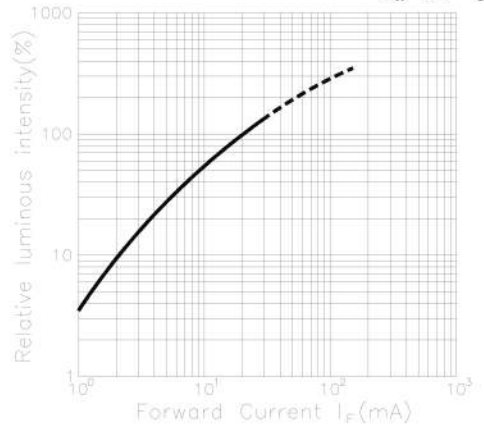


◆ Typical Electro-Optical Characteristic Curves:

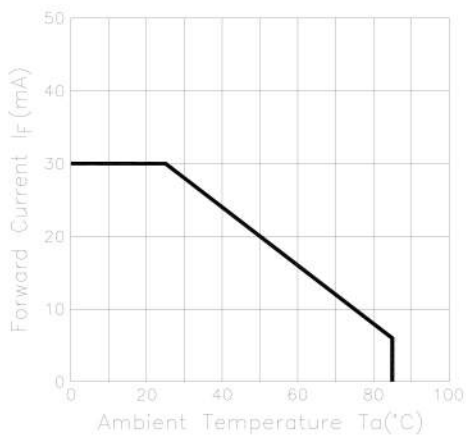
Forward Current Vs. Forward Voltage
Ta=25° C



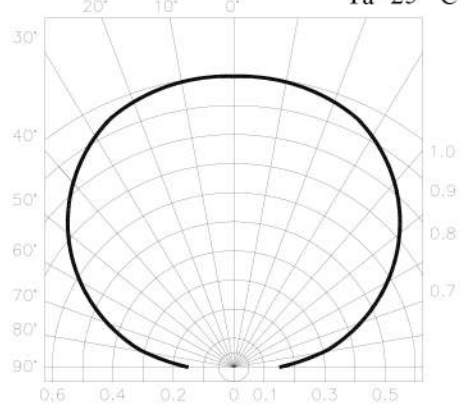
Luminous Intensity Vs. Forward Current
Ta=25° C



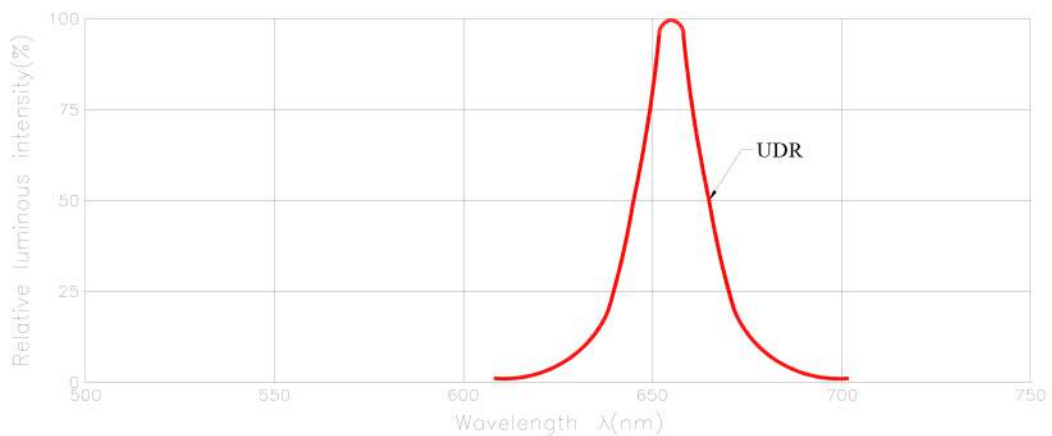
Forward Current Derating Curve



Radiation Diagram
Ta=25° C



Spectrum Distribution



◆Packing and Shipping Spec.

